L Number	Hits	Search Text	DB	Time stamp
1	38	"5252854"	USPAT;	2003/01/23 11:20
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	35	5252854.URPN.	USPAT	2003/01/23 10:42
3	1	("6081029").PN.	USPAT	2003/01/23 11:25
4	3	6081029.URPN.	USPAT	2003/01/23 11:24
5		("6452278").PN.	USPAT	2003/01/23 11:27
6	3153	257/666.ccls.	USPAT;	2003/01/23 11:39
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
l_ i		420 (000 and 1 and 2	IBM_TDB	2003/01/23 11:40
7	144	438/977.ccls. and lead\$2	USPAT; US-PGPUB;	2003/01/23 11:40
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	139	(438/977.ccls. and lead\$2) and	USPAT;	2003/01/23 13:18
8	139	(@ad<20000425)	US-PGPUB;	
		(000000000)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
9	1	("20020056926").PN.	US-PGPUB	2003/01/23 11:47
10	1	("6247229").PN.	USPAT	2003/01/23 11:50
11	5		USPAT	2003/01/23 11:48
12	2869	chip and (metal\$4 near (substrate or base))	USPAT;	2003/01/23 11:52
		and wire	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
13	436	(chip and (metal\$4 near (substrate or base))	USPAT;	2003/01/23 13:16
		and wire) and ((remov\$3 or thin\$4) near	US-PGPUB;	
		(substrate or base))	EPO; JPO;	
			DERWENT; IBM TDB	
14	105	((chip and (metal\$4 near (substrate or	USPAT;	2003/01/23 11:56
14	103	base)) and wire) and ((remov\$3 or thin\$4)	US-PGPUB;	2003/01/23 11.36
		near (substrate or base))) and encapsula\$3	EPO; JPO;	
		TITE (June 1 Table) / All	DERWENT;	
			IBM TDB	
15	69	(((chip and (metal\$4 near (substrate or	USPAT;	2003/01/23 11:59
		base)) and wire) and ((remov\$3 or thin\$4)	US-PGPUB;	
		near (substrate or base))) and encapsula\$3)	EPO; JPO;	
1		and (@ad<20000425)	DERWENT;	
			IBM_TDB	
17	1	("6380062").PN.	USPAT	2003/01/23 12:00
18	2	("5977633"   "6201292").PN.	USPAT	2003/01/23 12:01
19	0	6380062.URPN.	USPAT	2003/01/23 12:03
20	0	6380062.URPN.	USPAT	2003/01/23 12:03
21	0	6380062.URPN.	USPAT	2003/01/23 12:03
16	20	((thick and thin) near lead) and (die or chip) and wire\$5	USPAT; US-PGPUB;	2003/01/23 12:04
		CHIP/ and wiless	EPO; JPO;	
			DERWENT;	
			IBM TDB	
22	8712	lead and (die or chip) and wire\$5 and	USPAT;	2003/01/23 12:05
	3712	encapsula\$4	US-PGPUB;	= 300, 52, 23 12.05
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
23	1557		USPAT;	2003/01/23 12:08
		encapsula\$4) and ((etch\$3 or remov\$3 or	US-PGPUB;	
		thin\$4) near (substrate or base or metal\$4))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
			-	

0.4	1100	((lead and (die or chip) and wire\$5 and	USPAT;	2003/01/23 12:28
24	1102	encapsula\$4) and ((etch\$3 or remov\$3 or	US-PGPUB;	2003/01/23 12:28
ł			EPO; JPO;	
		thin\$4) near (substrate or base or	DERWENT;	
		metal\$4))) and (@ad<20000425)		
1		1/ 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	IBM_TDB	2003/01/23 12:47
25	960	((chip or die) near pad) and ((etch\$3 or	USPAT;	2003/01/23 12:4/
		remov\$3 or thin\$4) near (substrate or base	US-PGPUB;	
		or metal\$4))	EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	0000/01/00 10 40
26		20020074672.URPN.	USPAT	2003/01/23 12:43
27		("6211462").PN.	USPAT	2003/01/23 13:12
28	0	(think near pad) and lead and (chip or die)	USPAT;	2003/01/23 13:13
		and encapsula\$4	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
29	21	(thick near pad) and lead and (chip or die)	USPAT;	2003/01/23 13:15
		and encapsula\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
30	2399	leadless and chip	USPAT;	2003/01/23 13:15
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
32	241	(leadless and chip) and ((remov\$3 or thin\$4)	USPAT;	2003/01/23 13:18
		near (metal\$4 or substrate or base))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
33	207	((leadless and chip) and ((remov\$3 or	USPAT;	2003/01/23 13:19
		thin\$4) near (metal\$4 or substrate or	US-PGPUB;	
		base))) and (@ad<20000425)	EPO; JPO;	
			DERWENT;	
			IBM TDB	

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